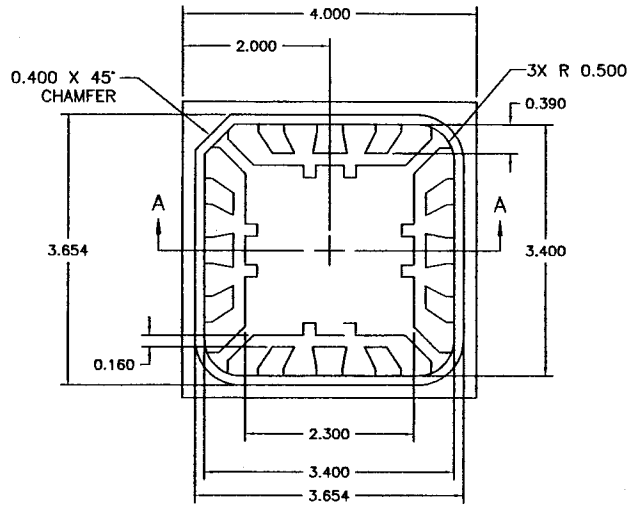
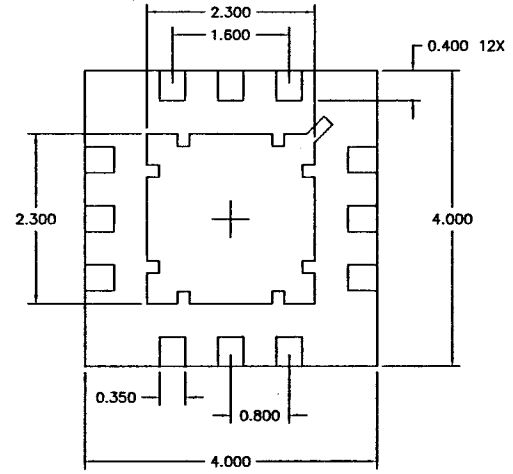
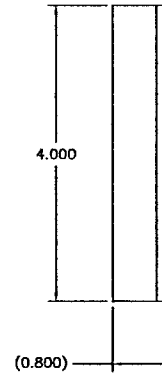


SSM P/N QFN01201

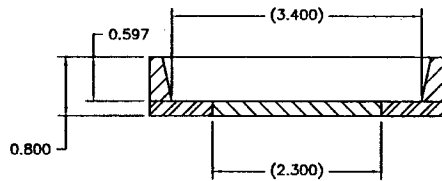
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEAD FRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL GOLD PLATE.
4. LEAD THICKNESS: 0.2030 ± 0.0076.
5. FRAME THICKNESS: 0.2030 ± 0.0076.
6. DIE PAD: 2.300mm X 2.300mm.
7. JEDEC OUTLINE: MO-220 (VGG6)

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

TOLERANCES ARE:
 X.XX ± 0.015 X.XXXX ± ---
 X.XXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	DATE
APP BY	DATE
CUSTOMER	---

12 Lead 4.00mm x 4.00mm

QFN4X4-012 REV 1

